



### Features

- ±2.0% Tolerance on Breakdown Voltage
- Small, Low Profile Surface Mount Package
- Flat Lead Package Design for Low Profile and High Power
  Dissipation
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

### SURFACE MOUNT PRECISION ZENER DIODE

#### **Mechanical Data**

- Case: SOD523
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Alloy 42 Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.001 grams (Approximate)



Top View

# Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging
BZT585B5V1TQ-7	Automotive	SOD523	3,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

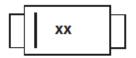
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/quality/product\_compliance\_definitions/.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



xx = Product Type Marking Code (See Electrical Characteristics Table)



### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.					
Chara	cteristic	Symbol	Value	Unit	
Forward Voltage	@ I <sub>F</sub> = 10mA @ I <sub>F</sub> = 100mA	VF	0.9 1.1	V	
Continuous Forward Current		I <sub>F</sub>	200	mA	

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	PD	350	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R <sub>θJA</sub>	357	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-65 to +150	°C

Note: 6. Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at http://www.diodes.com.

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

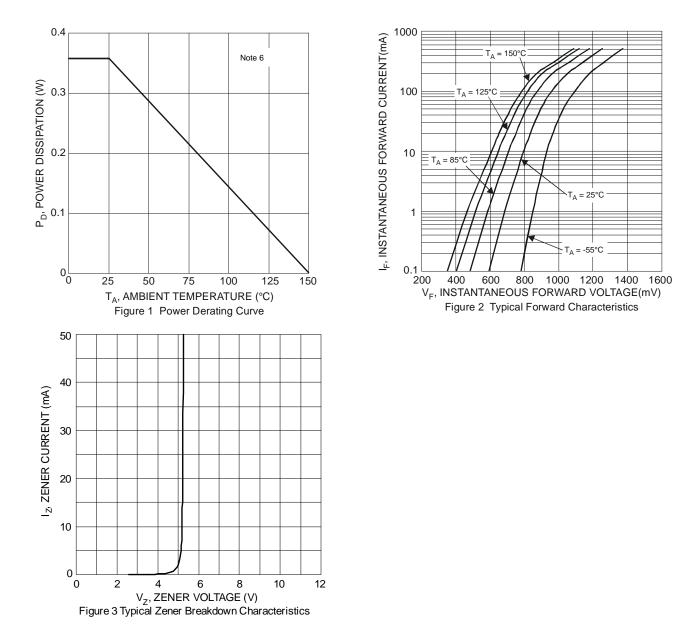
Туре	Marking	Zener Voltage Range (Note 7)		Maximum Zener Impedance (Note 8)		Temperature Coefficient	Total Capacitance	Maximum Reverse Current (Note 7)				
Number	Codes		Vz @ I <sub>ZT</sub>		I <sub>ZT</sub>	Z <sub>ZT</sub> @ I <sub>ZT</sub>	Z <sub>ZK</sub> @ I <sub>ZK</sub>	I <sub>ZK</sub>	TC @ I <sub>ZT</sub>	C <sub>T</sub> @ f = 1MHz, V <sub>R</sub> = 0V	I <sub>R</sub>	@ V <sub>R</sub>
		Nom (V)	Min (V)	Max (V)	mA	2	Ω	mA	Typical (mV/°C)	Max (pF)	μA	v
BZT585B5V1TQ	3N	5.1	5.00	5.20	5	60	480	1	-0.5	300	2	2

Notes: 7. Short duration pulse test used to minimize self-heating effect.

8. f = 1kHz.

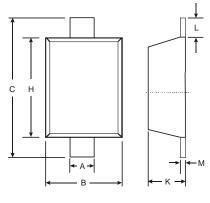


# BZT585B5V1TQ



# **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

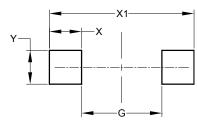


	SOD523					
Dim	Dim Min Max					
Α	0.25	0.35				
В	0.70	0.90				
С	1.50	1.70				
Н						
<b>K</b> 0.55 0.65						
L	L 0.10 0.30					
Μ	<b>M</b> 0.10 0.12					
All Dim	All Dimensions in mm					



# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.80
Х	0.60
X1	2.00
Y	0.70

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